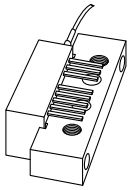


BGO807; BGO807/FC0; BGO807/SC0

870 MHz optical receivers

Rev. 2 — 29 September 2010 Product data sheet

1. Product profile

1.1 General description

High dynamic range optical receiver amplifier modules in a standard SOT115 package where the non-jacketed fiber has either no connector or has an FC/APC or SC/APC connector.

The amplifier supply voltage pin and the photo diode bias voltage pin both connect to 24 V (DC).

The modules have a mono mode optical input suitable for 1290 nm to 1600 nm wavelengths, a terminal to monitor the photo diode current and an electrical output having a characteristic impedance of 75 Ω.

CAUTION

This device is sensitive to ElectroStatic Discharge (ESD). Therefore care should be taken during transport and handling.

1.2 Features and benefits

- Excellent linearity
- Low noise
- Excellent flatness
- Standard CATV outline
- Rugged construction
- Gold metallization ensures excellent reliability
- High optical input power range.

1.3 Applications

- CATV optical node systems operating in the 40 MHz to 870 MHz frequency range.

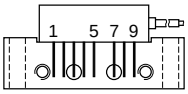
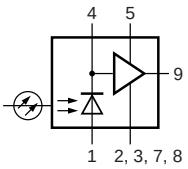
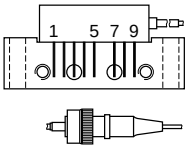
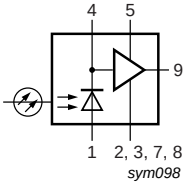
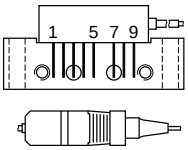
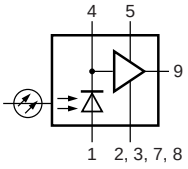
1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f	frequency range		40	-	870	MHz
s_{22}	output return losses	f = 40 MHz to 870 MHz	11	-	-	dB
	optical input return losses		45	-	-	dB
d_2	second order distortion	f = 854.5 MHz	-	-	–55	dB
F	equivalent noise input	f = 40 MHz to 870 MHz	-	-	8.5	pA/√Hz
I_{tot}	total current consumption (DC)	V_B = 24 V	175	-	205	mA

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
BGO807 (SOT115T)			
1	monitor current		
2, 3	common		
4	+V_B of the photodiode		
5	+V_B of the amplifier		
7, 8	common		
9	output		
BGO807/FC0 (SOT115X)			
1	monitor current		
2, 3	common		
4	+V_B of the photodiode		
5	+V_B of the amplifier		
7, 8	common		
9	output		
BGO807/SC0 (SOT115Y)			
1	monitor current		
2, 3	common		
4	+V_B of the photodiode		
5	+V_B of the amplifier		
7, 8	common		
9	output		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BGO807	-	rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 × 6-32 UNC and 2 extra horizontal mounting holes; optical input; 8 gold-plated in-line leads	SOT115T
BGO807/FC0	-	rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 × 6-32 UNC and 2 extra horizontal mounting holes; optical input with connector; 8 gold-plated in-line leads	SOT115X
BGO807/SC0	-	rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 × 6-32 UNC and 2 extra horizontal mounting holes; optical input with connector; 8 gold-plated in-line leads	SOT115Y

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
f	frequency range		40	870	MHz
T_{stg}	storage temperature		−40	+85	°C
T_{mb}	operating mounting base temperature		−20	+85	°C
P_{in}	optical input power	continuous	-	5	mW
ESD	ESD sensitivity	human body model; R = 1.5 kΩ; C = 100 pF	500	-	V

5. Characteristics

Table 5. Characteristics

In accordance with the Absolute Maximum Rating System (IEC 60134); bandwidth 40 MHz to 870 MHz; V_B = 24 V; T_{mb} = 30 °C; Z_L = 75 Ω.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
S	responsivity						
	BGO807	λ = 1300 nm		800	-	-	V/W
	BGO807/FC0; BGO807/SC0	λ = 1300 nm		750	-	-	V/W
FL	flatness straight line (peak to valley)	f = 40 MHz to 870 MHz		-	-	1	dB
SL	slope straight line	f = 40 MHz to 870 MHz		0	-	2	dB
s_{22}	output return losses	f = 40 MHz to 870 MHz		11	-	-	dB
	optical input return losses			45	-	-	dB
d_2	second order distortion	f_m = 446.5 MHz	[1][2]	-	-	−66	dB
		f_m = 746.5 MHz	[1][3]	-	-	−61	dB
		f_m = 854.5 MHz	[1][4]	-	-	−55	dB
d_3	third order distortion	f_m = 853.25 MHz	[5][6]	-	-	−71	dB

Table 5. Characteristics *...continued*

In accordance with the Absolute Maximum Rating System (IEC 60134); bandwidth 40 MHz to 870 MHz; V_B = 24 V; T_{mb} = 30 °C; Z_L = 75 Ω.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
F	equivalent noise input	f = 40 MHz to 450 MHz	-	-	7	pA/√Hz
		f = 450 MHz to 750 MHz	-	-	8	pA/√Hz
		f = 750 MHz to 870 MHz	-	-	8.5	pA/√Hz
s_λ	spectral sensitivity	λ = 1310 ±20 nm	0.85	-	-	A/W
		λ = 1550 ±20 nm	0.9	-	-	A/W
λ	optical wavelength		1290	-	1600	nm
L	length of optical fiber; SM type; 9/125 μm					
	BGO807		1	-	-	m
	BGO807/FC0; BGO807/SC0		746	-	861	mm
I_{tot}	total current consumption (DC)		175	-	205	mA
I_{bias}	diode bias current at pin 4 (DC)		-	-	25	mA

[1] Two laser test; each laser with a modulation index of 40%; P_{opt} = 1 mW (total).

[2] f_m = 446.5 MHz; f_p = 97.25 MHz; f_q = 349.25 MHz.

[3] f_m = 746.5 MHz; f_p = 133.25 MHz; f_q = 613.25 MHz.

[4] f_m = 854.5 MHz; f_p = 133.25 MHz; f_q = 721.25 MHz.

[5] Three laser test; each laser with a modulation index of 60%; P_{opt} = 1 mW (total).

[6] f_m = 853.25 MHz; f_p = 133.25 MHz; f_q = 265.25 MHz; f_r = 721.25 MHz.

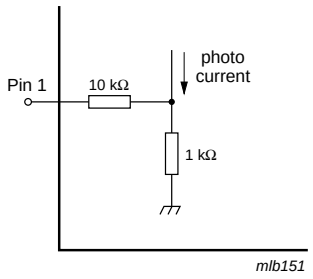
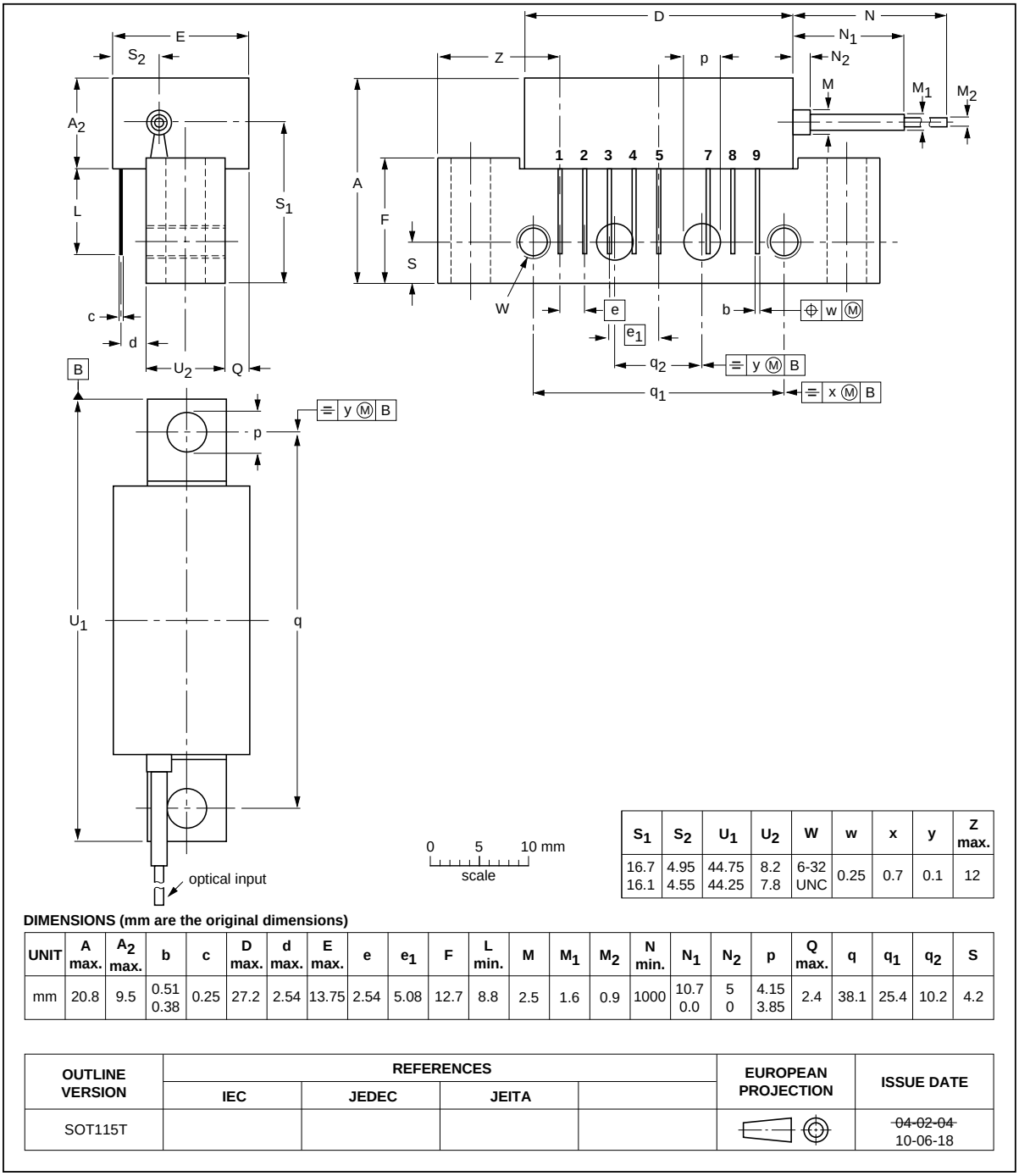


Fig 1. Monitor current pin.

6. Package outline

Rectangular single-ended package; aluminium flange; 2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes; optical input; 8 gold-plated in-line leads **SOT115T**



S_1	S_2	U_1	U_2	W	w	x	y	Z max.
16.7 16.1	4.95 4.55	44.75 44.25	8.2 7.8	6-32 UNC	0.25	0.7	0.1	12

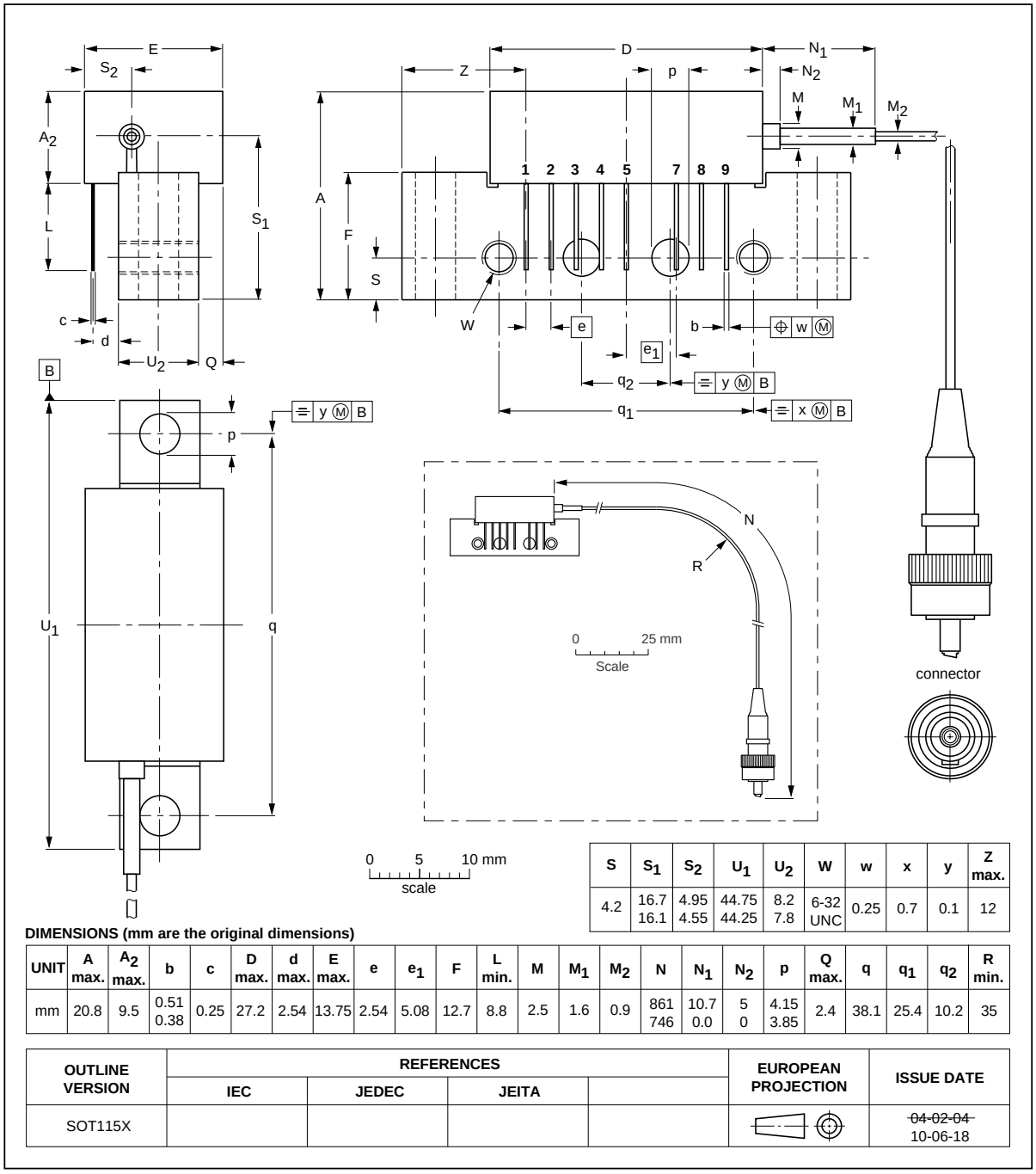
DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_2 max.	b	c	D max.	d max.	E max.	e	e_1	F	L min.	M	M_1	M_2	N min.	N_1	N_2	p	Q max.	q	q_1	q_2	S
mm	20.8	9.5	0.51 0.38	0.25	27.2	2.54	13.75	2.54	5.08	12.7	8.8	2.5	1.6	0.9	1000	10.7 0.0	5 0	4.15 3.85	2.4	38.1	25.4	10.2	4.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT115T						~~04-02-04~~ 10-06-18

Fig 2. Package outline SOT115T.

Rectangular single-ended package; aluminium flange;
2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes;
optical input with connector; 8 gold-plated in-line leads **SOT115X**



S	S_1	S_2	U_1	U_2	W	w	x	y	Z max.
4.2	16.7 16.1	4.95 4.55	44.75 44.25	8.2 7.8	6-32 UNC	0.25	0.7	0.1	12

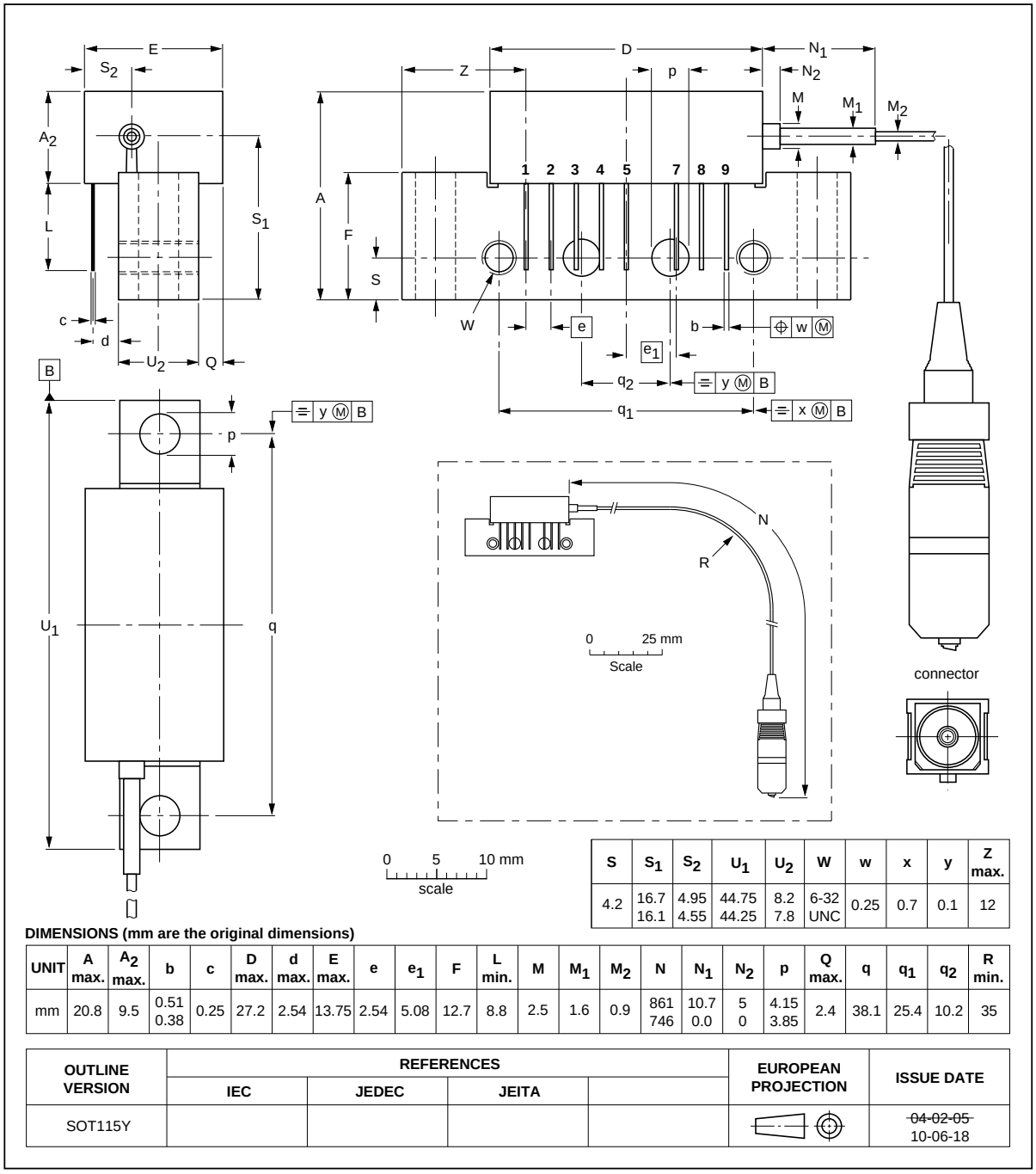
DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_2 max.	b	c	D max.	d max.	E max.	e	e_1	F	L min.	M	M_1	M_2	N	N_1	N_2	p	Q max.	q	q_1	q_2	R min.
mm	20.8	9.5	0.51 0.38	0.25	27.2	2.54	13.75	2.54	5.08	12.7	8.8	2.5	1.6	0.9	861 746	10.7 0.0	5 0	4.15 3.85	2.4	38.1	25.4	10.2	35

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT115X						~~04-02-04~~ 10-06-18

Fig 3. Package outline SOT115X.

Rectangular single-ended package; aluminium flange;
2 vertical mounting holes; 2 x 6-32 UNC and 2 extra horizontal mounting holes;
optical input with connector; 8 gold-plated in-line leads **SOT115Y**



S	S1	S2	U1	U2	W	w	x	y	Z max.
4.2	16.7 16.1	4.95 4.55	44.75 44.25	8.2 7.8	6-32 UNC	0.25	0.7	0.1	12

DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A2 max.	b	c	D max.	d max.	E max.	e	e1	F	L min.	M	M1	M2	N	N1	N2	p	Q max.	q	q1	q2	R min.
mm	20.8	9.5	0.51 0.38	0.25	27.2	2.54	13.75	2.54	5.08	12.7	8.8	2.5	1.6	0.9	861 746	10.7 0.0	5 0	4.15 3.85	2.4	38.1	25.4	10.2	35

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT115Y						~~04-02-05~~ 10-06-18

Fig 4. Package outline SOT115Y.

7. Handling information

Fiberglass optical coupling: maximum tensile strength = 5 N; minimum bending radius = 35 mm.

8. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BGO807_FC0_SC0 v.2	20100929	Product data sheet	-	BGO807_FC0_SC0 v.1
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Pinning information: presentation was modified, graphic symbols were added. • Package outline and simplified outline drawings have been updated to the latest version.			
BGO807_FC0_SC0 v.1 (9397 750 13192)	20040707	Product data sheet	-	-

9. Legal information

9.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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11. Contents

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